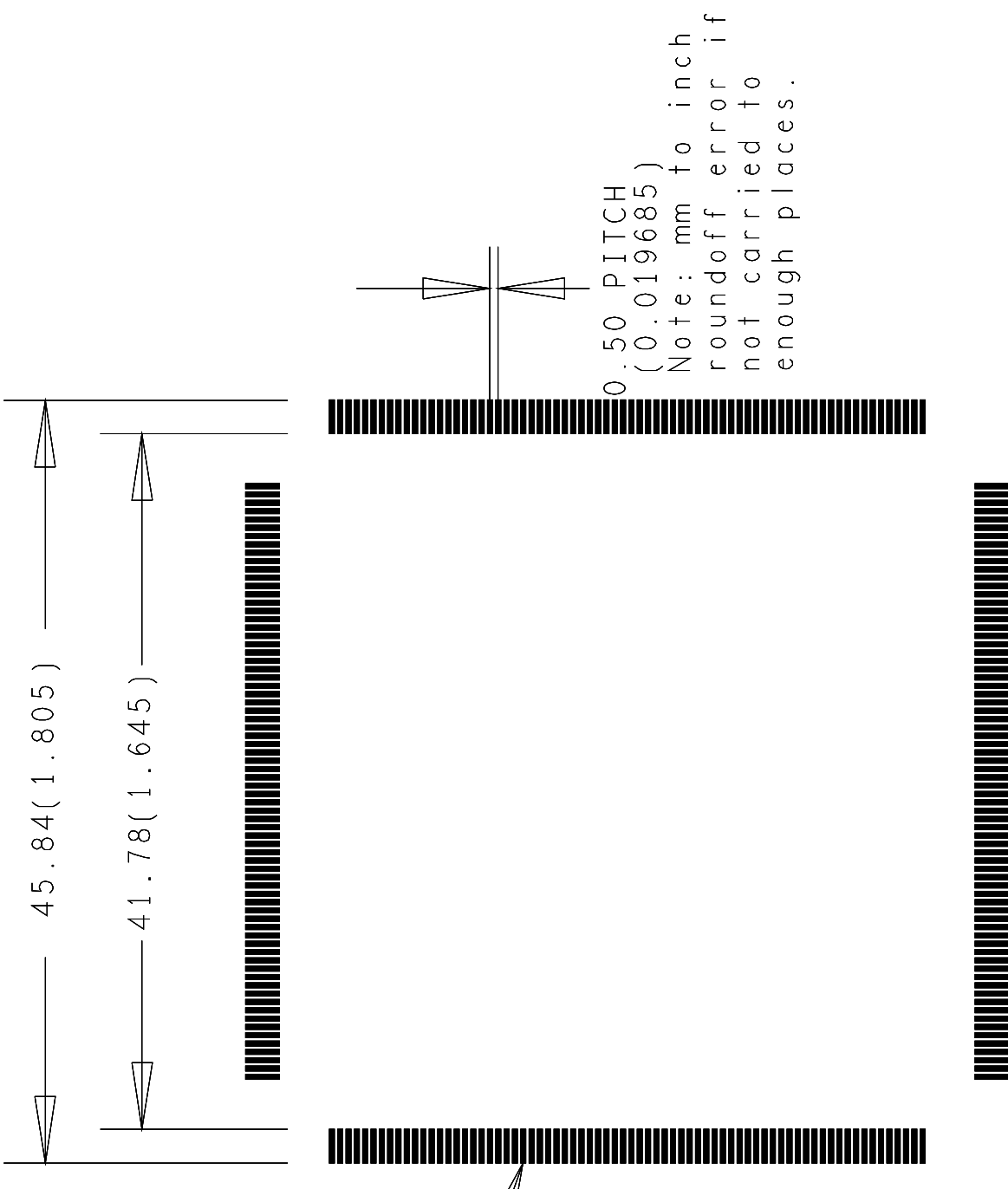


DIMENSIONS: mm(inches)



LEAD FORMING GUIDELINES:

APPLY THE FOLLOWING LEAD FORMING GUIDELINES TO ENSURE THE 288-LEAD CERAMIC QFP WILL FIT ONTO THIS FOOTPRINT.

- 1) FIRST LEAD BEND IS 1.14 ±.13 (.045 ±.005) FROM THE BODY.
- 2) SECOND LEAD BEND IS MADE 2.67 -0/+ .51 (.105 -0/+ .020) TO ALLOW PWB TO COMPONENT BODY CLEARANCE.
- 3) THE HEAL OF THE FOOT IS OFFSET FROM THE FIRST BEND BY 0-.46 (0-.018).
- 4) THE FOOT OF THE LEAD IS 1.14 ±.13 (.045 ±.005).

THESE LEAD FORMING GUIDELINES ARE COMPATABLE WITH IPC/EIA J-STD-001C FOR NOMINAL SOLDER FILLETS AND IPC-SM-782 FOR LAND PATTERN DESIGN.

RECOMMENDED FOOTPRINT FOR AEROFLEX
288-PIN CERAMIC QUAD FLAT PACKAGE (CQFP)